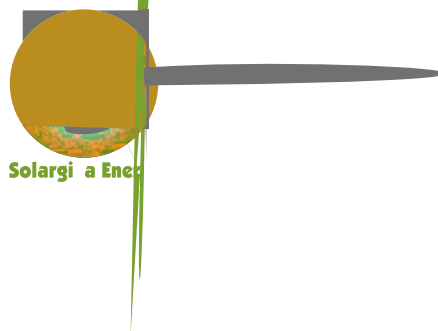


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The gross proceeds of the Bond Issue in the amount of RMB300 million, after deduction of commission, professional fee and other administrative expenses, are arranged in order to be used for general corporate purposes.

On August 24, 2011, the Board of Directors of the Company has resolved to issue the Bond Issue. The details of the Bond Issue are as follows:

This announcement is made pursuant to Rule 13.09(1) of the Listing Rules.

Reference is made to the announcement of the Company dated 15 August 2011 in relation to the Bond Issue.

The Board is pleased to announce that on 19 August 2011, the Company and the Manager have entered into the Subscription Agreement for the purpose of the Bond Issue. Details of the Subscription Agreement are set out below:

1. The Manager

Date: 19 August 2011

Parties: (1) Company
(2) the Manager

Subject to the satisfaction and/or waiver of the conditions set out below under the section headed "SUBSCRIPTION AGREEMENT" Condition Precedent of the Subscription Agreement set out below, the Manager has agreed, on a best-effort basis and subject to the terms of the Subscription Agreement, to subscribe and pay for or procure to subscribe and pay for the Bond of RMB300,000,000. The Bond are to be issued at 100% of the aggregate principal amount.

The Bond will be offered only to persons outside the United States in reliance on Regulation S under the Securities Act. None of the Bond will be offered to the public in Hong Kong or elsewhere.

To the best of the Director's knowledge, information and belief having made all reasonable enquiries, the Manager and its ultimate beneficial owner are third parties independent of the Company and its connected persons (as defined in the Listing Rules).

The obligation of the Manager to subscribe and pay or procure subscription and payment for the Bonds are conditional on the satisfaction and/or fulfilment of, among other things:

(i) all representations and warranties and other agreements of the Company in the Subscription Agreements are, as and at the Closing Date, true and correct reference to the facts and circumstances then existing;

(ii) the

ing;

Subject to the foregoing, the Bond Interest is expected to be completed and issued on the Closing Date.

The principal terms of the Bond, which will be contained in the Fiscal Agency Agreement, are summarized as follows:

- (1) Issuer: the Company
- (2) Manager: SinoPac Securities (Asia) Limited
- (3) Principal amount: The aggregate principal amount of the Bond will be RMB300,000,000.
- (4) Issue Price: 100% of the aggregate principal amount of the Bond
- (5) Issue Date: 24 August 2011, or such other date as the Company and the Manager may agree in writing
- (6) Maturity: Unless previously redeemed or purchased and cancelled, the Bond will be redeemed at their principal amount on the interest payment date falling on 24 August 2014. The Bond may not be redeemed at the option of the Company or other than in accordance with the terms and conditions of the Bond.
- (7) Interest: The Bond will bear interest from 24 August 2011 at the rate of 4.75% per annum, payable semi-annually, in arrears on 24 February and 24 August in each year, commencing on 24 February 2012.

(8) Redemption for
a reason

- (9) Purchase The Company and its subsidiaries may at any time purchase the Bond (provided that, in the case of Bond represented by the global bond, such Bonds are purchased together with the right to receive payment of interest hereon and, in the case of any defined bond, all rights and claims appertaining hereon are surrendered here to) in the open market or by private resale at a price.
- (10) Taxation and Withholding All payments of principal and/or interest in respect of the Bond and the related coupon will be made free and clear of, and without withholding or deduction for or on account of, any present or future tax, duty, assessment or governmental charge of whatsoever nature imposed or levied, withheld or assessed by or on behalf of Hong Kong, the Cayman Islands, Taiwan or the PRC or any political subdivision or any authority hereof or herein having power to levy a tax in Hong Kong, the Cayman Islands, Taiwan or the PRC, in each case without withholding or deduction required by the law of the jurisdiction. In addition, the Company shall pay such additional amount as will result in the receipt by the Bondholder of such amount as would have been received by them if no such withholding or deduction had been required, provided, however, that no such additional amount shall be payable in respect of any Bond presented for payment under certain circumstances as described in the terms and conditions of the Bond.
- (11) Events of Default The Bond will contain certain events of default, including a cross default provision as described in the terms and conditions of the Bond.
- (12) Clearance and Settlement The Bond will be issued in bearer form and initially represented by a global bond deposited with a sub-agent for the CMU.
- (13) Denomination The denomination of the Bond is RMB100,000 each.
- (14) Ranking of the Bond The Bond constitutes (subject to the terms and conditions of the Bond) direct, unconditional, non-subordinated and unsecured obligations of the Company, at all times ranking *pari passu* with any preference among them and, subject to the terms and conditions of the Bond, ranking at least *pari passu* with all other present and future direct, unconditional, non-subordinated and unsecured obligations of the Company other than any such obligations preferred by provision of law that have both mandatory and of general application.

The Bond will not be liable on an exchange change.

The gross proceeds of the Bond Issue in the amount of RMB300 million, after deduction of commission, professional fee and other administrative expenses, are currently intended to be used for general corporate purposes.

The Group is one of the leading manufacturers of monocrystalline silicon ingots and wafers in China by production capacity. The Group is principally engaged in (a) manufacturing and

In this announcement, the following expressions shall have the following meanings, unless the context indicates otherwise:

Board	the board of Directors
Bondholder(s)	holder(s) of the Bond from time to time
Bond	the RMB300,000,000 4.75% bond due in 2014 to be issued by the Company
Bond Issue	the issue of the Bond by the Company
Closing Date	24 August 2011, or such other date, as the Company and the Manager may agree in writing
CMU	Central Money Market Unit service operated by the HKMA
Company	Solargiga Energy Holding Limited, an exempted company incorporated in the Cayman Islands with limited liability, the ordinary shares of which are listed on the main board of the Stock Exchange of Hong Kong

Subscription Agreement

The subscription agreement, dated 19 August 2011 entered into between the Company and the Manager in relation to the Bond Issue

United States or U.S.

The United States of America